

Remarks

This amendment is submitted in response to the Office Action of April 1, 2003.

Claims 1-20 are pending. Claims 19 and 20 are withdrawn. Claims 1 and 4-7 are currently amended. Claims 2, 3, 8 and 9 are original. Claims 10-18 are canceled.

The Examiner objected to the specification because the cross-reference to related patent applications did not include the serial number and filing date. Paragraph 1 of specification has been amended to add the serial number and filing date to the cross-referenced application.

The Applicant has also deleted, in its entirety, paragraph 19.

The Examiner rejected claims 1-18 under 35 USC §102(b) as being anticipated by Ohara et al. (US patent 5,688,033). Claims 10-18 are not canceled. Claim 1 has been amended in several respects. The claim now recites "forming" an enclosure having a plurality of air-cavity covers, wherein each of the covers as a "vent hole." In claim 4, "forming" is defined as "molding." Claim 1 also adds a number of new process steps. Among the steps are

"applying a curable adhesive between said enclosure and said carrier,
aligning said enclosure with the carrier such that each component is covered by one of said air-cavity covers;

curing said adhesive, said vent hole providing for the escape of water and other gasses that may off-gas during the curing process from said air cavity; sealing said vent holes with a curable material; curing said sealing material..."

Ohara et al. discloses a silicon wafer process for forming an air cavity for enclosing a component. A silicon wafer is patterned into a plurality of air cavities and adhered to a silicon substrate by depositing gold at the interface between the two silicon bodies and heating it above 360° Celsius. At this temperature, gold and silicon dissolve into each other in a eutectic process. This is entirely different process than claimed by the applicant that calls for the use of a curable adhesive to mate the covers to the carrier. A curing process, as opposed to a eutectic process, vents gas and moisture.

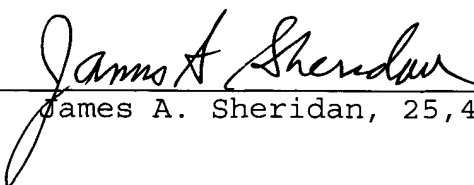
There is no disclosure in Ohara et al. of a vent hole in each cover to allow the venting of air and moisture from the cavity during its heating process. Not only does Ohara et al. not disclose vent holes in each air cavity cover, Ohara et al. contains no suggestion to modify its eutectic process into a curable adhesive process. Applicant therefore respectfully submits that Applicant's claim 1, as amended, defines over Ohara et al. both a lack of disclosure of a vent hole and the use of a curable adhesive, but because it fails to suggest any basis for modifying its process into applicant's claimed process.

Claim 4 also defines the enclosure formation process as being a molding process. Ohara covers are formed from a silicon wafer using etching or some other such process. Regardless of

how such cavities are formed, however, they are not molded or moldable as now required by claim 4.

Applicant respectfully submits that all claims are allowable over the reference(s) of record.

Respectfully submitted,

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